AGENDA

Symposium on Chemical-Mechanical Planarization
August 12-15, 2007
Hilton Lake Placid Resort

Sunday, August 12:

12:00 - 5:00 P.M.	Hotel Check-in and CAMP Registration
5:45 - 7:00 P.M.	Cocktail Reception being held at The Olympic Regional Development, Olympic Center, 2634 Main Street,(No formal dinner provided)
6:15 - 7:30 P.M.	Dancing Bears Lounge: For those arriving late – light hors d'oeuvres and a drink on CAMP

Monday, August 13:

7:00 - 8:00 A.M.	Breakfast - Terrace Room

MEETING HELD IN MEDALLION ROOM

8:00 A.M.	**S.V. Babu: Opening Remarks**

Session I

8:10 A.M.	"Integration of Porous Low K Dielectrics: Materials & Metrology Challenges" -- Mansour Moinpour, Intel Corporation.
8:35 A.M.	"Damageless Cu-CMP for Porous Low-k/Cu Interconnects" -- Seiichi Kondou, Selete
9:00 A.M.	"EC(M)P - can we do it without the M" --Karl Hensen, BASF
9:25 A.M.	"Comparison of the Planarization Technologies for the Next Generation" -- Itsuki Kobata, Ebara Corporation
9:50 A.M.	Coffee Break

Session II

10:15 A.M.	"CMP Technology Trends and Markets" -- Karey Holland, Techcet Group, LLC
10:40 A.M.	"Defectivity Mechanisms in CMP: Barrier and W CMP Processes" -- Ajoy Zutshi, DA Nano
11:05 A.M.	"The Effect of Consumables on CMP Defect Reduction" -- Picheng Huang, Praxair
11:30 A.M.	"The Recent Advances in CMP Process Characterization Wafers" -- Sookap Hahn, SKW
11:55 A.M.	Discussion
12:00 P.M.	Lunch - Terrace Room

Monday, August 13 Continued:

Session III

3:20 P.M.	"Recent Advancements in Fixed Abrasive STI CMP" -- John Gagliardi, 3M Company
3:45 P.M.	"Cerium Oxide Manufacturing Process Control and Particle Morphology Effects on Defectivity for Future STI SMP Slurries" – David Merricks, Ferro Electronic
4:10 P.M.	"Impact of Ceria Properties and CMP Parameters on STI CMP Performance" -- Jo De Messemaeker, Umicore
4:35 P.M.	"HARP CMP Removal Profile Alteration Through Slurry Dispense Position" -- Matthew Smalley, IBM Albany
5:00 P.M.	"Characterization of CMP Consumables: Opportunities and Challenges" -- RK Singh, Entegris
5:30 – 7:00 P.M.	Poster Session/ Open Bar – Medallion Room (note: day changed)
7:00 P.M.	Dinner
	After Dinner Speaker: TBD

Tuesday, August 14:

7:00 - 8:00 A.M.	Breakfast -Terrace Room

Session IV

8:05 A.M.	"Enabling Solutions for 45 nm Node" -- Manabu. Tsujimura, Ebara Corporation
8:30 A.M.	"Advanced CMP Consumables for 32nm Generation" -- Masayuki Motonari, JSR Corporation
8:55 A.M.	"Advanced Cu & Barrier CMP Slurry for 65-45nm Technology" -- ShinodaTakashi, Hitachi Chemical Co., Ltd.
9:20 A.M.	"Effect of Slurry pH on Ru CMP" -- Jin-Goo Park, Hanyang University
9:45 A.M.	Coffee Break

Session V

10:15 A.M.	"On the Relationship Between Contact Area Data and Polishing" -- L. Borucki, Araca, Inc.
10:40 A.M.	"The Impact of CMP Pad-Wafer Contact on Slurry Particle Flow at the Asperity Scale" Gregory Muldowney, Rohm and Haas

Tuesday, August 14 Continued:

11:05 A.M.	“Investigation of CMP Pad Contact Characteristics by Computational Modeling and In-Situ Measurement”-- Bo Jiang, Carolina Elmufdi, and Gregory Muldowney, Rohm and Haas
11:30 A.M.	"Effect of Concentric Slanted Groove Patterns on Slurry Flow During Copper CMP” D. Rosales-Yeomans University of Arizona
11:55 A.M.	Discussion
12:00 P.M.	Lunch – Terrace Room

Session VI

3:30 P.M.	“LPC formation in Collodial Silica based CMP Slurries” -- Scott Rader, Fujimi
3:55 P.M.	“Origin of Various CMP Defects” -- Paul LeFevre, Innopad
4:20 P.M.	"Advancements in Pad Conditioning for Tungsten Chemical Mechanical Planarization” --Tammy Engfer, 3M Company
4:45 P.M.	“Study of Pad Surface Treatment for the Improvement of the Process Performance and the Productivity” -- Akira Isobe, Nitta-Haas Incorporated
5:10 P.M.	Discussion
6:00 - 7:00 P.M.	Reception at Lake Placid Club
7:00 P.M.	Dinner at Lake Placid Club

Wednesday, August 15:

7:00 - 8:00 A.M.	Breakfast - Terrace Room

Session VII

8:05 A.M.	“Impact of Bevel Polish Cleaning on Wafer Surface Defects” -- Yoshikuni Tateyama, Toshiba Corporation
8:30 A.M.	“In-situ Ellipsometric Study on the "Condensation" and "Cleaning" of a Metalorganic Copper Compound to/from Porous k Thin Films in Supercritical Carbon Dioxide” -- Eiichi Kondoh, University of Yamanashi
8:55 A.M.	“In Situ Friction Coefficient Measurements During Metal CMP for Polishing Process Stabilize” -- Yohei Yamada Hitachi, Ltd.
9:20 A.M.	“Development of Novel Post CMP Cleaning Solution” -- Sunny Xu, Anji Microelectronics, Shanghai China
9:45 A.M.	“Developing Products for CMP Requires a Module-Level Approach, Peter Wrschka, ATMI, Inc. and Robert Rhoades, Entrepix, Inc
10:05 A.M.	Break

Wednesday, August 15 Continued:

Session VIII

10:30 A.M. “Impact of Chloride Ions on Copper CMP” -- Intel

10:55 A.M. “Grind Silicon Wafer Polishing - Providing Industry Ultraflat Si Substrate”
-- Lily Yao, Strasbaugh

11:20 A.M. “Novel High Purity, pH Stable Colloidal Slurry”
-- B. Mullee, R. Small, S. Holland, and K. Holland, Silco

11:45 P.M. “CMP of Moisture Sensitive Materials”
-- Yuzhuo Li, CAMP

12:10 P.M. Closing Remarks, S.V. Babu, CAMP

12:15 P.M. Lunch - Terrace Room